# +3.3V, 10.3Gbps Limiting Amplifier 

## General Description

The MAX3971 is a compact, low-power, 10.3Gbps limiting amplifier. It accepts signals over a wide range of input voltage levels and provides constant-level output voltages with controlled edge speeds. It functions as a data quantizer. The output of the amplifier is a 250 mV P-p differential CML signal with a $100 \Omega$ differential termination.
The MAX3971 is designed to work with the MAX3970, a 10.3Gbps transimpedance amplifier (TIA). The limiting amplifier operates on a single +3.3 V supply and consumes only 155 mW . The part functions over the $0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ temperature range. It also has a disable function that allows the outputs to be squelched if required by the application.
The MAX3971 is offered in die form and in a compact $4 \mathrm{~mm} \times 4 \mathrm{~mm}, 20$-pin QFN plastic package.

## Applications

10-Gigabit Ethernet Optical Receivers
VSR OC-192 Receivers
10-Gigabit Fibre Channel Receivers

Features

- Single +3.3V Power Supply
- 155mW Power Consumption
-9.5mVP-P Input Sensitivity
- 800mVp-p Input Overload
- 3.4psp-p Deterministic Jitter
- Dice and 4mm x 4mm QFN Packages
- Output Disable Feature

Ordering Information

| PART | TEMP. RANGE | PIN-PACKAGE | PKG <br> CODE |
| :---: | :--- | :--- | :---: |
| MAX3971UGP | $0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 20 QFN | G2044-4 |
| MAX3971U/D | $0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | Dice* $^{*}$ | - |

*Dice are designed to operate over a $0^{\circ} \mathrm{C}$ to $+110^{\circ} \mathrm{C}$ junction temperature ( $T_{J}$ ) range, but are tested and guaranteed at $T_{A}=+25^{\circ} \mathrm{C}$.

Pin Configuration appears at end of data sheet.

Typical Application Circuit


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## ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $\mathrm{V}_{\mathrm{CC}} 1, \mathrm{~V}_{\mathrm{CB}}, \mathrm{V}_{\mathrm{CC}}$
$3 .$. $\qquad$ .-0.5 V to +0.5 V Voltage at $\mathrm{IN}+$, IN-, DISABLE,

CZ+, CZ-, OUT+, OUT-........................ 0.5 V to (VCC +0.5 V )
Differential Voltage Between CZ+ and CZ- .......................... $\pm 1 \mathrm{~V}$
Differential Voltage Between IN+ and IN- $\qquad$
Continuous Power Dissipation $\left(\mathrm{T}_{\mathrm{A}}=+85^{\circ} \mathrm{C}\right)$
20-Lead QFN (derate $20 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+85^{\circ} \mathrm{C}$ ) .............. 1.3 W

Operating Ambient Temperature Range .............. $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ Storage Temperature Range ............................. $-55^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Die Attach Temperature................................................... $+400^{\circ} \mathrm{C}$
Lead Temperature (soldering, 10s) ................................. $+300^{\circ} \mathrm{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS

$\left(\mathrm{V}_{\mathrm{CC}}=+3.0 \mathrm{~V}\right.$ to $+3.6 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{V}_{\mathrm{CC}}=+3.3 \mathrm{~V}$, output load $=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted. Data mark density is $50 \%$.)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Supply Current | Icc |  |  | 47 | 85 | mA |
| Small-Signal Bandwidth | BW |  |  | 10 |  | GHz |
| Low-Frequency Cutoff |  | $C Z=0.1 \mu \mathrm{~F}$ |  | 40 | 160 | kHz |
| Data Rate |  |  |  | 10 |  | Gbps |
| Deterministic Jitter |  | 10 mV P-p input, K28.5 pattern at 10.3 Gbps (Note 1) |  | 8 |  | pSP-P |
|  |  | 20 mV P-P input, K28.5 pattern at 10.3 Gbps (Note 1) |  | 4.7 | 14 |  |
|  |  | 800 mV P-p input, K28.5 pattern at 10.3 Gbps (Note 1) |  | 3.4 | 7 |  |
| Random Jitter |  | $20 \mathrm{mV} \mathrm{P}_{\text {-P }}$ to 800mVP-P (Note 2) |  | 0.7 | 1.0 | psRms |
| Transition Time, Output | $\mathrm{tr}_{\mathrm{r}} \mathrm{tf}$ | 20\% to 80\%, OUT+, OUT- |  | 20 | 30 | ps |
| Input Sensitivity | VIN-min | $\mathrm{BER}=1 \mathrm{E}-12,2^{23}-1 \mathrm{PRBS}$, 10.3Gbps |  |  | 9.5 | mVP-P |
| Input Overload | VIN-max |  | 800 |  |  | mVP-P |
| Data Input Resistance | RIN | Single-ended | 42 | 52 | 58 | $\Omega$ |
| Differential Data <br> Output-Voltage Swing | VOD1 | DISABLE high |  | 1 | 50 | mVP-P |
|  | VOD2 | DISABLE low | 190 | 250 | 400 |  |
| Data Output Common-Mode Voltage | VCM |  |  | $\begin{gathered} \text { VCC - } \\ 0.75 \end{gathered}$ |  | V |
| Output Resistance | Rout | Single-ended | 42 | 52 | 58 | $\Omega$ |
| Data Output Offset when DISABLE is High |  |  |  | 75 |  | mVP-P |
| DISABLE Input Current |  | High = VCC, low = GND |  | 0.05 | 1 | mA |
| DISABLE Input High Voltage |  |  | 2.8 |  |  | V |
| DISABLE Input Low Voltage |  |  |  |  | 1.4 | V |

Note 1: Deterministic jitter is measured with a K28.5 pattern (0011 111010110000 0101). It is the peak-to-peak deviation from the ideal time crossings, measured at the zero-level crossings of the differential output.
Note 2: Random jitter is measured with the minimum input signal applied. To achieve a bit error rate of $10^{-12}$, the peak-to-peak random jitter is 14.1 times the RMS random jitter.

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 Typical Operating Characteristics$\left(\mathrm{V}_{\mathrm{CC}}=+3.3 \mathrm{~V}\right.$, output load $=50 \Omega$ to $\mathrm{VCC}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted. $)$


TRANSITION TIME vs. TEMPERATURE (20\% to 80\%)


INPUT SENSITIVITY vs. TEMPERATURE (FOR BIT-ERROR RATIO OF 1E-12)


OUTPUT EYE DIAGRAM
(INPUT SIGNAL $=800 \mathrm{mV}$ P.p AT 10.3Gbps)


20ps/div

DETERMINISTIC JITTER vs. TEMPERATURE ( 800 mV P.P INPUT K28.5 PATTERN AT 10.3Gbps)


INPUT RETURN (S11)
INPUT SIGNAL $=\mathbf{- 2 0 d B m}$


OUTPUT EYE DIAGRAM
(INPUT SIGNAL = 9mVp.p AT 10.3Gbps)


20ps/div

DETERMINISTIC JITTER vs. TEMPERATURE (10mVp.p INPUT K28.5 PATTERN AT 10.3Gbps)


OUTPUT RETURN (S22) INPUT SIGNAL =-20dBm


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## Typical Operating Characteristics (continued)

$\left(\mathrm{V}_{\mathrm{CC}}=+3.3 \mathrm{~V}\right.$, output load $=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


Pin Description

| PIN | NAME |  |
| :---: | :---: | :--- |
| 1 | GNDIN+ | Input Ground for Shielding Input Signal IN+. Not connected internally. |
| 2 | IN+ | Noninverting Input Signal |
| 3 | IN- | Inverting Input Signal |
| 4 | GNDIN- | Input Ground for Shielding Input Signal IN-. Not connected internally. |
| $5,7,9,10$ | N.C. | No Connection. Leave unconnected. |
| $6,8,11$ | GND | Ground |
| 12,15 | VCC3 | Output Circuitry Power Supply |
| 13 | OUT- | Inverting Output of Amplifier |
| 14 | OUT+ | Noninverting Output of Amplifier |
| 16 | DISABLE | When High, the Outputs are Disabled |
| 17 | VCC2 | Power Supply to Circuitry Other than Input and Output Circuits |
| 18 | CZ+ | Filter Capacitor for Offset Correction. Attach other side of a capacitor to pin 19. See the Detailed <br> Description. |
| 19 | CZ- | See pin 18. |
| 20 | VCC1 | Input Circuitry Power Supply |
| EP | Exposed <br> Pad | Exposed Pad. Must be soldered to supply ground for proper electrical and thermal operation. |

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## Detailed Description and Applications Information

Figure 1 is a functional diagram of the MAX3971 limiting amplifier. The signal path consists of an input buffer followed by a gain stage and output amplifier. A feedback loop provides offset correction by driving the average value of the differential output to zero.

Gain Stage and Offset Correction
The limiting amplifier provides approximately 50dB gain. This large gain makes the amplifier susceptible to small DC offsets, which cause deterministic jitter. A low-frequency loop is integrated into the limiting amplifier to reduce output offset, typically to less than 2 mV .

The external capacitor CZ is required to set the low-frequency cutoff for the offset correction loop and for stability. The time constant of the loop is set by the


Figure 1. Functional Diagram


Figure 2. CML Input Equivalent Circuit
product of an equivalent $20 \mathrm{k} \Omega$ on-chip resistor and the value of the off-chip capacitor, CZ. For stable operation, the minimum value of CZ is $0.01 \mu \mathrm{~F}$. To minimize pattern-dependent jitter, CZ should be as large as possible. For 10-Gigabit Ethernet applications, the typical value of CZ is $0.1 \mu \mathrm{~F}$. Keep CZ as close to the package as possible.

CML Input Circuit
The input buffer is designed to accept CML input signals such as the output from the MAX3970 transimpedance amplifier. An equivalent circuit for the input is shown in Figure 2. DC-coupling the inputs is not recommended because doing so prevents the part's offset correction circuitry from working properly. Thus, ACcoupling capacitors are required on the input.

CML Output Circuit
An equivalent circuit for the output network is shown in Figure 3. It consists of two $50 \Omega$ resistors connected to VCC driven by the collectors of an output differential transistor pair (Q1 and Q2). The differential output signals are clamped by transistors Q3 and Q4 when the DISABLE input is high.

Disable Function
A logic signal can be applied to the DISABLE pin to squelch the output signal. When the output is disabled, an offset is added to the output, preventing the following stage from oscillating (if DC-coupled).


Figure 3. CML Input Equivalent Circuit Showing Clamping Circuit for Squelching the Output Signal

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## Layout Considerations

Circuit board layout and design can significantly affect the MAX3971's performance. Use good high-frequency techniques, including fixed-impedance transmission lines for the high-frequency data signal. Use a multilayer board with solid ground plane. Minimize the inductance between MAX3971 and the ground plane.
The MAX3971 uses three power supply pins (VCC1, Vcc2, Vcc3). The input circuitry of the MAX3971 is supplied by $\mathrm{V}_{\mathrm{Cc}} 1$. The output drivers have a separate supply (VCC3), which usually has large pulsing currents. All other circuitry is powered by Vcc2. It is possible to simply connect the three pins together. However, better isolation of the input circuitry is ensured by using a supply filter. For optimal isolation, Figure 4 shows a possible supply filtering circuit. Element L, a ferrite bead, provides isolation between a noisy $\mathrm{V}_{\mathrm{CC}} 3$ and sensitive VCC1.


Figure 4. Power-Supply Filter

Chip Information
TRANSISTOR COUNT: 1803
PROCCESS: SiGe Bipolar
SUBSTRATE: Electrically Isolated

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## Chip Topography (continued)

| MAX3971 |  |  |
| :---: | :---: | :---: |
| PIN NUMBER | X DIMENSION <br> (MICRONS) | Y DIMENSION <br> (MICRONS) |
| 1 | 0 | 672 |
| 2 | 0 | 546 |
| 3 | 0 | 420 |
| 4 | 0 | 294 |
| 5 | 0 | 168 |
| 6 | 163.8 | 0 |
| 7 | 289.8 | 0 |
| 8 | 415.8 | 0 |
| 9 | 541.8 | 0 |
| 10 | 667.8 | 0 |
| 11 | 884.8 | 168 |
| 12 | 884.8 | 294 |
| 13 | 884.8 | 420 |
| 14 | 884.8 | 546 |
| 15 | 884.8 | 672 |
| 16 | 667.8 | 772.8 |
| 17 | 541.8 | 772.8 |
| 18 | 415.8 | 772.8 |
| 19 | 289.8 | 772.8 |
| 20 | 163.8 | 772.8 |

- All dimensions are in microns.
- Pad dimensions:

PASSIVATION OPENING: 94.4 microns $\times$ 94.4 microns

METAL: 102.4 microns $\times 102.4$ microns

- All measurements specify the lower left corner of the pad



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(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)


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## NOTES:

1. DIE THICKNESS ALLOWABLE IS 0.305 mm MAXIMUM (. 012 INCHES MAXIMUM).
2. DIMENSIONING \& TOLERANCES CONFORM MUST TO ASME Y14.5M. - 1994.
3. $N$ IS THE NUMBER OF TERMINALS. Nd IS THE NUMBER OF TERMINALS IN X-DIRECTION \&
Ne IS THE NUMBER OF TERMINALS IN Y-DIRECTION.
4. dimension b applies to plated terminal and is measured BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
5. THE PIN *1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR INK/LASER MARKED. DETAILS OF PIN \#1 IDENTIFIER IS OPTIONAL, BUT MUST BE LOCATED WITHIN ZONE INDICATED.
6. Exact shape and size of this feature is optional.
7. ALL DIMENSIONS ARE IN MILLIMETERS.
8. PACKAGE WARPAGE MAX 0.05 mm .

9. APPLIED FOR EXPOSED PAD AND TERMINALS. exclude embedding part of exposed pad from measuring.
10. MEETS JEDEC MO220; EXCEPT DIMENSION "b".
11. this package outline apples to punched qfn (stepped sides).


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